

Vishay General Semiconductor

# Surface-Mount TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier



Anode O Cathode

## LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS						
I <sub>F(AV)</sub>	3 A					
V <sub>RRM</sub>	100 V					
I <sub>FSM</sub>	80 A					
V <sub>F</sub> at I <sub>F</sub> = 1.5 A (T <sub>J</sub> = 125 °C)	0.43 V					
T <sub>J</sub> max.	150 °C					
Package	DFN3820A					
Circuit configuration	Single					

### FEATURES

- Low profile package typical height of 0.88 mm
- Leadless DFN package with side-wettable flanks suitable for customer AOI (Automatic Optical Inspection)
- Trench MOS Schottky technology
- Low power losses, high efficiency
- Low forward voltage drop
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
   Automotive ordering code; base P/NHM3
- Compatible to SMP (DO-220AA) package case outline
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### **TYPICAL APPLICATIONS**

For use in low voltage, high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

#### **MECHANICAL DATA**

#### Case: DFN3820A

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test **Polarity:** color band denotes the cathode end

<b>MAXIMUM RATINGS</b> ( $T_A = 25 \text{ °C}$ unless otherwise noted)							
PARAMETER	SYMBOL	V3N103	UNIT				
Device marking code		V3G					
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	100	V				
Maximum average forward rectified current (fig. 1)	I <sub>F(AV)</sub> <sup>(1)</sup>	3	А				
Maximum average forward rectilied current (lig. 1)	I <sub>F(AV)</sub> <sup>(2)</sup>	1.8	А				
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	80	A				
Operating junction temperature range	T <sub>J</sub> <sup>(3)</sup>	-40 to +150	°C				
Storage temperature range	T <sub>STG</sub>	-55 to +150	°C				

Notes

(1) Mounted on 10 mm x 10 mm copper pad area PCB

<sup>(2)</sup> Free air, mounted on FR4 PCB, 2 oz., standard footprint

 $^{(3)}$  The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ 

 Revision: 06-Nov-2024
 1
 Document Number: 98442

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<b>ELECTRICAL CHARACTERISTICS</b> ( $T_J = 25 \text{ °C}$ unless otherwise noted)								
PARAMETER	TEST CO	ONDITIONS	SYMBOL	TYP.	MAX.	UNIT		
	I <sub>F</sub> = 1.5 A	T <sub>J</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.50	-	V		
Instantanoous forward voltage	$I_{F} = 3.0 \text{ A}$	1j=25 C		0.60	0.66			
Instantaneous forward voltage	I <sub>F</sub> = 1.5 A	T <sub>J</sub> = 125 °C		0.43	-			
	I <sub>F</sub> = 3.0 A	1J=125 C		0.54	0.60			
	V <sub>R</sub> = 70 V	T <sub>J</sub> = 25 °C T <sub>J</sub> = 125 °C	I <sub>R</sub> (2)	0.0022	-			
Reverse current	$v_{\rm R} = 70$ v	T <sub>J</sub> = 125 °C		1.5	-	mA		
neverse current	$V_{-} = 100 V_{-}$	T <sub>J</sub> = 25 °C T <sub>J</sub> = 125 °C		-	0.2			
	v <sub>R</sub> = 100 v	T <sub>J</sub> = 125 °C		3.5	10			
Typical junction capacitance	4.0 V, 1 MHz		CJ	410	-	pF		

#### Notes

<sup>(1)</sup> Pulse test: 300 µs pulse width, 1 % duty cycle

<sup>(2)</sup> Pulse test: pulse width  $\leq$  5 ms

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25 \text{ °C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TYP.	MAX.	UNIT			
Thermal resistance	R <sub>0JA</sub> (1)(2)	135	169	°C/W			
	R <sub>0JM</sub> <sup>(3)</sup>	5	6.3	0/10			

#### Notes

<sup>(1)</sup> The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{0JA}$ 

(2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint

<sup>(3)</sup> Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

### **ORDERING INFORMATION TABLE**

**Device code** 

v		3	Ν	10	3	н	М3		
		2	3	4	5	6	7		
1	-	Visł	nay TME	3S produ	uct				
2	-	- Current rating (3 = 3 A)							
3	-	Pac	Package type (N = DFN3820A)						
4	-	Volt	Voltage rating (10 = 100 V)						
5	-	TM	TMBS generation option (3 = Gen3)						
6	-	Qua	Quality grade (H = AEC-Q101 qualified, otherwise = industry grade						
7	-	Mat	Material / Environment category (M3 = halogen-free,						

 Material / Environment category (M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free)

ORDERING INFORMATION (Example)								
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE				
V3N103-M3/H	0.023	Н	3500	7" diameter plastic tape and reel				
V3N103-M3/I	0.023	I	14 000	13" diameter plastic tape and reel				
V3N103HM3/H <sup>(1)</sup>	0.023	Н	3500	7" diameter plastic tape and reel				
V3N103HM3/I <sup>(1)</sup>	0.023	I	14 000	13" diameter plastic tape and reel				

Note

(1) AEC-Q101 qualified

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## **RATINGS AND CHARACTERISTICS CURVES** (T<sub>A</sub> = 25 °C unless otherwise noted)

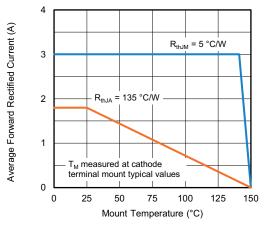


Fig. 1 - Maximum Forward Current Derating Curve

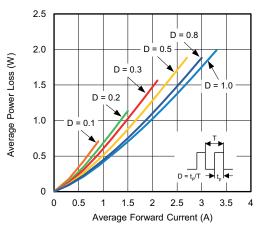


Fig. 2 - Forward Power Loss Characteristics

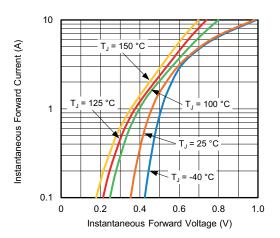


Fig. 3 - Typical Instantaneous Forward Characteristics

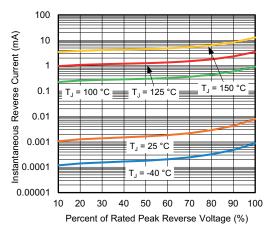


Fig. 4 - Typical Reverse Characteristics

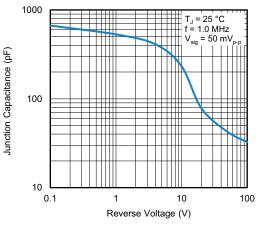


Fig. 5 - Typical Junction Capacitance

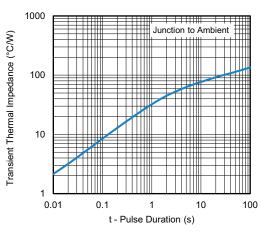


Fig. 6 - Typical Transient Thermal Impedance

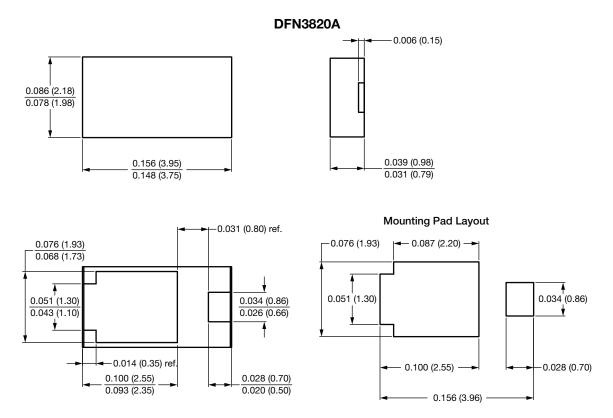
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### PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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Revision: 01-Jan-2025

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